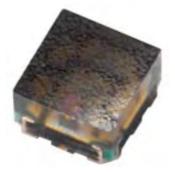


DATASHEET

SMD ■ EAST1010RGBA8



Features

- Package in 8mm tape on 7["] diameter reel
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow
- Solder process
- Full-color type
- Pb-free
- Component solderable surface finish is Gold
- The Product itself will remain whithn RoHS compliant version
- Compliance with EU REACH
- Compliance Halogen Free.(Br<900ppm,Cl<900ppm,Br+Cl<1500ppm)

Description

 EAST1010RGBA8 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained. Moreover, with its black PCB, the EAST1010RGBA8 possess an ideal solution for high-contract and high-resolution indoor signage display.

Applications

- Indoor signage display applications.
- Indoor decorating and entertainment design.
- Flat backlight for LCD, switch and symbol.
- Indicator and backlighting for all consumer electronics.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Red	
InGaN	Brilliant Green	Black Surface Diffused
InGaN	Brilliant Blue	

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
		R6:10	
Forward Current	lF	GA:10	mA
		BD:10	
Peak Forward Current		R6:20	
	I _{FP}	GA:20	mA
(Duty 1/10 @1KHz)		BD:20	
		R6:24	
Power Dissipation	Pd	GA:31	mW
		BD:31	
Junction Temperature	Tj	100	°C
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +90	°C
ESD		R:2000	
(Classification acc. AEC	ESDHBM	G:1000	V
Q101)		B:1000	
Reflow Soldering : 260 $^{\circ}$ C for 10 sec.			: 260 °C for 10 sec.
Soldering Temperature	T _{sol}	Hand Soldering :	350 °℃ for 3 sec.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	I	Min.	Тур.	Max.	Unit	Condition
		R6	18.0		39.5		
Luminous Intensity	lv	GA	56.0		94.7	mcd	I⊧=5mA
		BD	8.0		17.7		
Viewing Angle	20 1/2			120		deg	I⊧=5mA
		R6		625			
Peak Wavelength	Λр	GA		525		nm	I⊧=5mA
		BD		465			
		R6	619.0		626.0		
Dominant Wavelength	Λd	GA	523.5		532.5	nm	I⊧=5mA
		BD	463.5		472.5		
Spectrum Rediction		R6		20			
Spectrum Radiation Bandwidth	Δλ	GA		25		nm	I⊧=5mA
Bandwidth		BD		25			
		R6	1.7	2.0	2.4		
Forward Voltage	VF	GA	2.5	2.9	3.2	V	I⊧=5mA
		BD	2.5	2.9	3.2		
Reverse Current ⁴	IR				10	μA	V _R =5V

Note:

1. Tolerance of Luminous Intensity: ±10%

2. Tolerance of Dominant Wavelength: ±1nm

3. Tolerance of Forward Voltage: ±0.1V

4. Only for Electronic test

Floating Bin(R6) Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
RA	18.0	23.4		
RC	23.4	30.4	mcd	I⊧ =5mA
RE	30.4	39.5	_	

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
R2	619.0	624.0		
R3	621.0	626.0	– nm	I _F =5mA

Bin Range of Dominant Voltage

Bin Code	Min.	Max.	Unit	Condition
R1	1.7	2.4	V	l⊧ =5mA

Note:

1.Tolerance of Luminous Intensity: ±10%

2. Tolerance of Dominant Wavelength: ±1nm

3. Tolerance of Forward Voltage: ±0.1V

Floating Bin(GA) Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
GB	56.0	72.8		
GD	72.8	94.7	- mcd	l⊧ =5mA

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
G2	523.5	526.5		
G3	525.5	528.5		
G4	527.5	530.5	nm	I _F =5mA
G5	529.5	532.5		

Bin Range of Dominant Voltage

Bin Code	Min.	Max.	Unit	Condition
G1	2.5	3.2	V	I _F =5mA

Note:

- 1.Tolerance of Luminous Intensity: ±10%
- 2. Tolerance of Dominant Wavelength: ±1nm
- 3. Tolerance of Forward Voltage: ±0.1V

Floating Bin(BD) Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
BA	8.0	10.4		
BC	10.4	13.6	mcd	I⊧ =5mA
BE	13.6	17.7	_	

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
B2	463.5	466.5		
B3	465.5	468.5	-	I _F =5mA
B4	467.5	470.5	nm	
B5	469.5	472.5		

Bin Range of Dominant Voltage

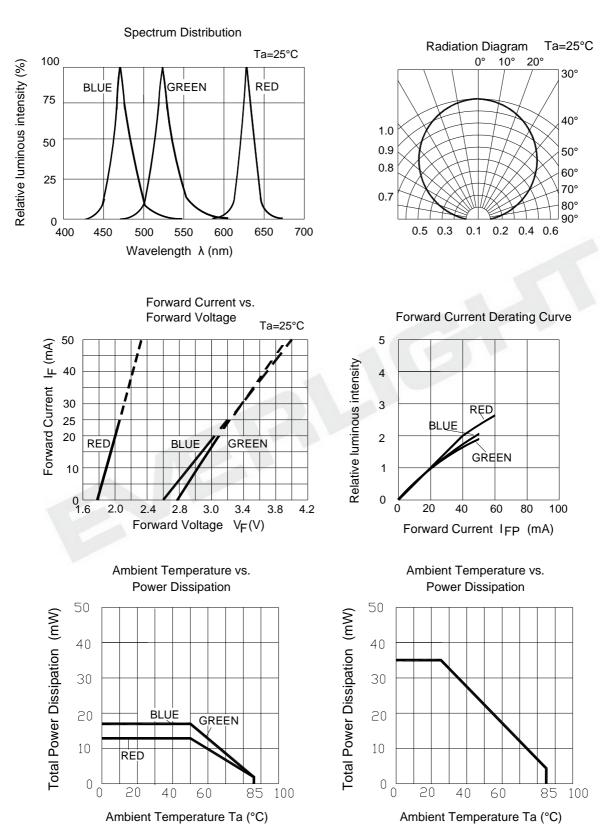
Bin Code	Min.	Max.	Unit	Condition
B1	2.5	3.2	V	I⊧ =5mA

Note:

1.Tolerance of Luminous Intensity: ±10%

2. Tolerance of Dominant Wavelength: ±1nm

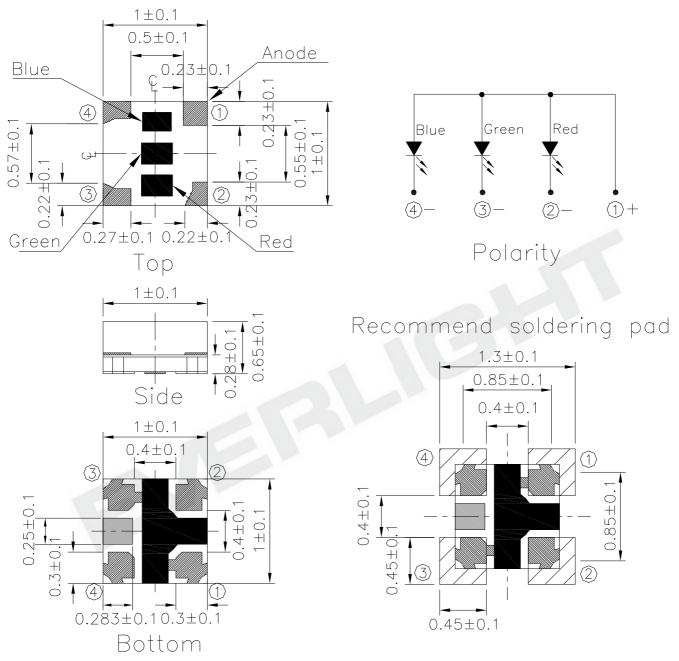
3. Tolerance of Forward Voltage: ±0.1V



Typical Electro-Optical Characteristics Curves

AMERICAS

Package Dimension



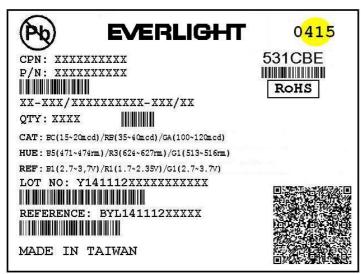
Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1mm. Unit = mm



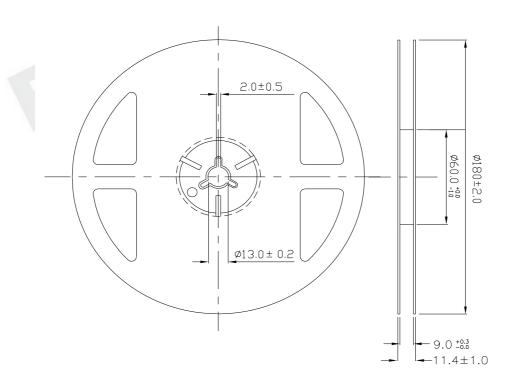
Moisture Resistant Packing Materials

Label Explanation



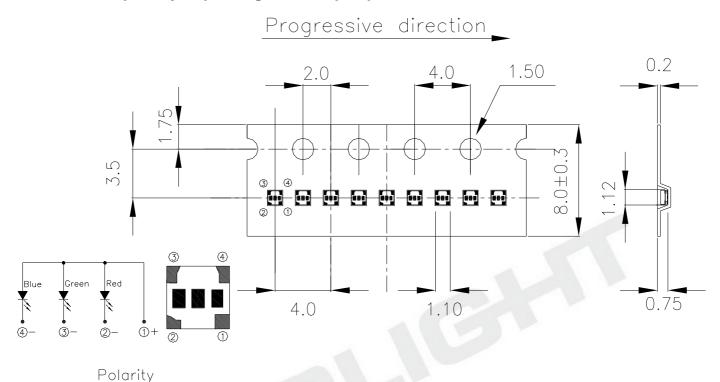
- PN: Customer's Product Number
- SPECIFICATION: LED
- PO TYPE: the label's function
- LOT No: Lot Number
- QTY: Packing Quantity
- VENDOR P/N: express the product type
- VENDOR/Code: EVERLIGHT'code

Reel Dimensions



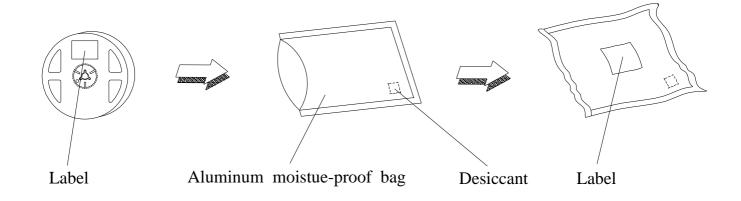
Carrier Tape Dimensions:

The minimum quantity of packing is 10000 pcs per reel.



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

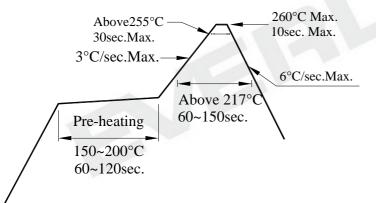


Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
 - 2.1 Do not open moisture proof bag before the products are ready to use.
 - 2.2 Before opening the package: The LEDs should be kept at 30° C or less and 90%RH or less.
 - 2.3 After opening the package: The LED's floor life is 168Hrs under 30° C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
 - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment : 60±5℃ for 24 hours.
 - 2.5 Before using LEDs, baking treatment should be implemented based on the following conditions: pre-curing at 60±5℃ for 24 hours or 125±5℃ for 3 hours.
- 3. Soldering Condition
 - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

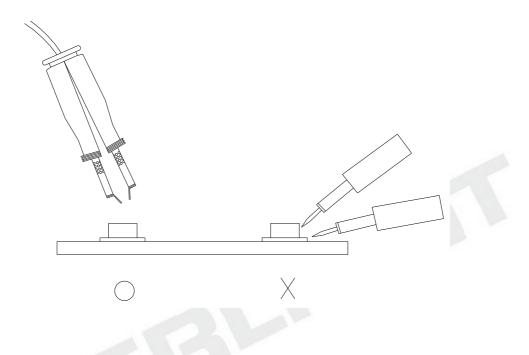
4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.



5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



6.Directions for use

The LEDs should be operated with forward bias. The driving circuit must be designed so that the LEDs are not subjected to forward or reverse voltage while it is off. If reverse voltage is continuously applied to the LEDs, It may cause migration resulting in LED damage.

DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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- 6. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.